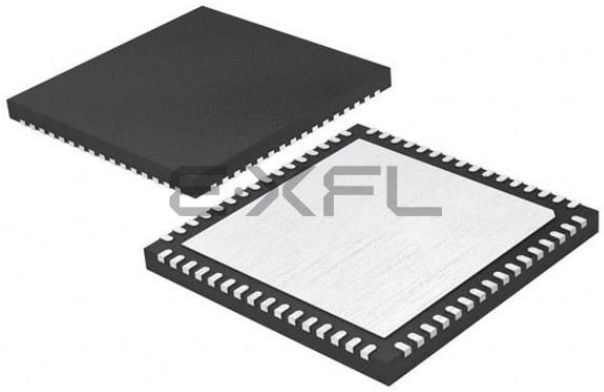
Microchip Technology - DSPIC33EP128GM306-I/MR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

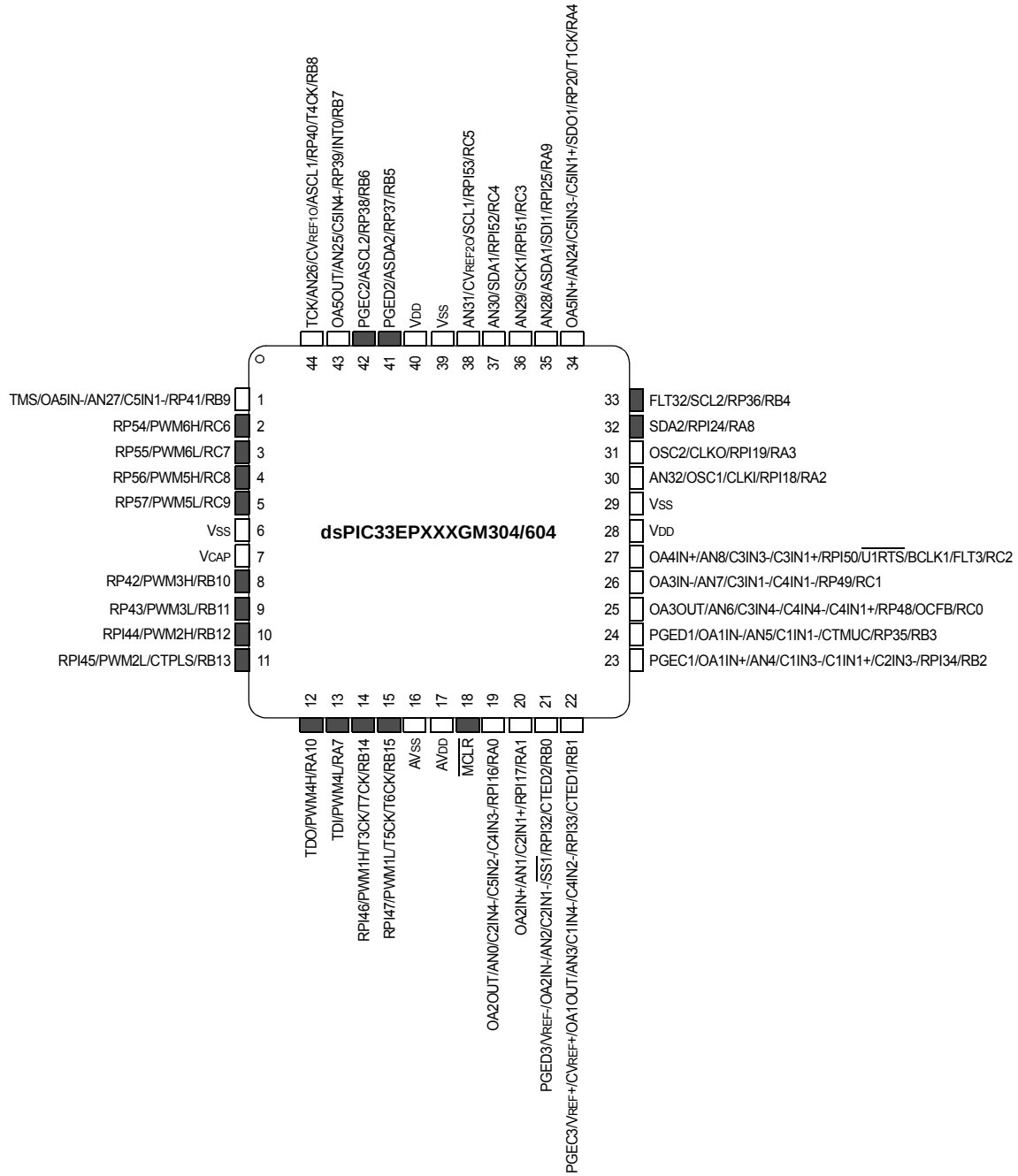
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 30x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gm306-i-mr

Pin Diagrams

44-Pin TQFP(1,2)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site:

- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

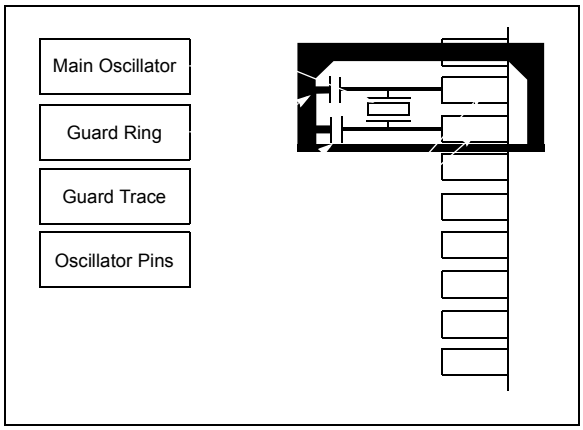


TABLE 4-4: TIMERS REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																0000
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																0000
TMR3HLD	0108	Timer3 Holding Register (For 32-bit timer operations only)																xxxx
TMR3	010A	Timer3 Register																0000
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR4	0114	Timer4 Register																0000
TMR5HLD	0116	Timer5 Holding Register (For 32-bit timer operations only)																xxxx
TMR5	0118	Timer5 Register																0000
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR6	0122	Timer6 Register																0000
TMR7HLD	0124	Timer7 Holding Register (For 32-bit timer operations only)																xxxx
TMR7	0126	Timer7 Register																0000
PR6	0128	Period Register 6																FFFF
PR7	012A	Period Register 7																FFFF
T6CON	012C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T7CON	012E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR8	0130	Timer8 Register																0000
TMR9HLD	0132	Timer9 Holding Register (For 32-bit timer operations only)																xxxx
TMR9	0134	Timer9 Register																0000
PR8	0136	Period Register 8																FFFF
PR9	0138	Period Register 9																FFFF
T8CON	013A	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T9CON	013C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-30: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGM304/604 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP49R<5:0>						—	—	RP48R<5:0>						0000
RPOR6	068C	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR7	068E	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-31: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGM306/706 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP49R<5:0>						—	—	RP48R<5:0>						0000
RPOR6	068C	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR7	068E	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000
RPOR8	0690	—	—	RP70R<5:0>						—	—	RP69R<5:0>						0000
RPOR9	0692	—	—	RP97R<5:0>						—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

In addition, DMA transfers can be triggered by timers as well as external interrupts. Each DMA channel is unidirectional. Two DMA channels must be allocated to read and write to a peripheral. If more than one channel receives a request to transfer data, a simple fixed priority scheme, based on channel number, dictates which channel completes the transfer and which channel, or channels, are left pending. Each DMA channel moves a block of data, after which, it generates an interrupt to the CPU to indicate that the block is available for processing.

The DMA Controller provides these functional capabilities:

- Four DMA channels
- Register Indirect with Post-increment Addressing mode
- Register Indirect without Post-increment Addressing mode
- Peripheral Indirect Addressing mode (peripheral generates destination address)
- CPU interrupt after half or full block transfer complete
- Byte or word transfers
- Fixed priority channel arbitration
- Manual (software) or automatic (peripheral DMA requests) transfer initiation
- One-Shot or Auto-Repeat Block Transfer modes
- Ping-Pong mode (automatic switch between two SRAM Start addresses after each block transfer complete)
- DMA request for each channel can be selected from any supported interrupt source
- Debug support features

The peripherals that can utilize DMA are listed in Table 8-1.

TABLE 8-1: DMA CHANNEL TO PERIPHERAL ASSOCIATIONS

Peripheral to DMA Association	DMAxREQ Register IRQSEL<7:0> Bits	DMAxPAD Register (Values to Read from Peripheral)	DMAxPAD Register (Values to Write to Peripheral)
INT0 – External Interrupt 0	00000000	—	—
IC1 – Input Capture 1	00000001	0x0144 (IC1BUF)	—
IC2 – Input Capture 2	00000101	0x014C (IC2BUF)	—
IC3 – Input Capture 3	00100101	0x0154 (IC3BUF)	—
IC4 – Input Capture 4	00100110	0x015C (IC4BUF)	—
OC1 – Output Compare 1	00000010	—	0x0906 (OC1R) 0x0904 (OC1RS)
OC2 – Output Compare 2	00000110	—	0x0910 (OC2R) 0x090E (OC2RS)
OC3 – Output Compare 3	00011001	—	0x091A (OC3R) 0x0918 (OC3RS)
OC4 – Output Compare 4	00011010	—	0x0924 (OC4R) 0x0922 (OC4RS)
TMR2 – Timer2	00000111	—	—
TMR3 – Timer3	00001000	—	—
TMR4 – Timer4	00011011	—	—
TMR5 – Timer5	00011100	—	—
SPI1 Transfer Done	00001010	0x0248 (SPI1BUF)	0x0248 (SPI1BUF)
SPI2 Transfer Done	00100001	0x0268 (SPI2BUF)	0x0268 (SPI2BUF)
SPI3 Transfer Done	01011011	0x02A8(SPI3BUF)	0x02A8(SPI3BUF)
UART1RX – UART1 Receiver	00001011	0x0226 (U1RXREG)	—
UART1TX – UART1 Transmitter	00001100	—	0x0224 (U1TXREG)
UART2RX – UART2 Receiver	00011110	0x0236 (U2RXREG)	—
UART2TX – UART2 Transmitter	00011111	—	0x0234 (U2TXREG)
UART3RX – UART3 Receiver	01010010	0X0256(U3RXREG)	—
UART3TX – UART3 Transmitter	01010011	—	0X0254(U3TXREG)
UART4RX – UART4 Receiver	01011000	0X02B6(U4RXREG)	—
UART4TX – UART4 Transmitter	01011001	—	0X02B4(U4TXREG)

REGISTER 11-12: RPINR16: PERIPHERAL PIN SELECT INPUT REGISTER 16

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEB2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEA2R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **QEB2R<6:0>:** Assign QEI2 Phase B (QEB2) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **QEA2R<6:0>:** Assign A QEI2 Phase A (QEA2) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 16-14: PHASEx: PWMx PRIMARY PHASE-SHIFT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PHASEx<15:0>:** Phase-Shift Value or Independent Time Base Period for the PWMx Generator bits

Note 1: If ITB (PWMCONx<9>) = 0, the following applies based on the mode of operation:
Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), PHASEx<15:0> = Phase-shift value for PWMxH and PWMxL outputs.

2: If ITB (PWMCONx<9>) = 1, the following applies based on the mode of operation:
Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), PHASEx<15:0> = Independent Time Base Period Value for PWMxH and PWMxL.

REGISTER 16-15: SPHASEx: PWMx SECONDARY PHASE-SHIFT REGISTER(1,2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SPHASEx<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SPHASEx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **SPHASEx<15:0>:** Secondary Phase Offset for PWMxL Output Pin bits
(used in Independent PWM mode only)

Note 1: If ITB (PWMCONx<9>) = 0, the following applies based on the mode of operation:
- Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), SPHASEx<15:0> = Not used.
- True Independent Output mode (PMOD<1:0> (IOCONx<11:10>) = 11), SPHASEx<15:0> = Phase-Shift Value for PWMxL only.

2: If ITB (PWMCONx<9>) = 1, the following applies based on the mode of operation:
- Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), SPHASEx<15:0> = Not used.
- True Independent Output mode (PMOD<1:0> (IOCONx<11:10>) = 11), SPHASEx<15:0> = Independent Time Base Period Value for PWMxL only.

REGISTER 16-19: IOCONx: PWMx I/O CONTROL REGISTER(2)

R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PENH	PENL	POLH	POLL	PMOD1(1)	PMOD0(1)	OVRENH	OVRENL
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PENH:** PWMxH Output Pin Ownership bit
1 = PWMx module controls the PWMxH pin
0 = GPIO module controls the PWMxH pin

bit 14 **PENL:** PWMxL Output Pin Ownership bit
1 = PWMx module controls the PWMxL pin
0 = GPIO module controls the PWMxL pin

bit 13 **POLH:** PWMxH Output Pin Polarity bit
1 = PWMxH pin is active-low
0 = PWMxH pin is active-high

bit 12 **POLL:** PWMxL Output Pin Polarity bit
1 = PWMxL pin is active-low
0 = PWMxL pin is active-high

bit 11-10 **PMOD<1:0>:** PWMx # I/O Pin Mode bits(1)
11 = PWMx I/O pin pair is in the True Independent Output mode
10 = PWMx I/O pin pair is in Push-Pull Output mode
01 = PWMx I/O pin pair is in Redundant Output mode
00 = PWMx I/O pin pair is in Complementary Output mode

bit 9 **OVRENH:** Override Enable for PWMxH Pin bit
1 = OVRDAT<1> controls the output on the PWMxH pin
0 = PWMx generator controls the PWMxH pin

bit 8 **OVRENL:** Override Enable for PWMxL Pin bit
1 = OVRDAT<0> controls the output on the PWMxL pin
0 = PWMx generator controls the PWMxL pin

bit 7-6 **OVRDAT<1:0>:** Data for PWMxH, PWMxL Pins if Override is Enabled bits
If OVERENH = 1, PWMxH is driven to the state specified by OVRDAT<1>.
If OVERENL = 1, PWMxL is driven to the state specified by OVRDAT<0>.

bit 5-4 **FLTDAT<1:0>:** Data for PWMxH and PWMxL Pins if FLTMOD is Enabled bits
If Fault is active, PWMxH is driven to the state specified by FLTDAT<1>.
If Fault is active, PWMxL is driven to the state specified by FLTDAT<0>.

bit 3-2 **CLDAT<1:0>:** Data for PWMxH and PWMxL Pins if CLMOD is Enabled bits
If current limit is active, PWMxH is driven to the state specified by CLDAT<1>.
If current limit is active, PWMxL is driven to the state specified by CLDAT<0>.

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).
2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 17-19: INTxHLDH: INTERVAL TIMERx HOLD HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **INTHLD<31:16>:** Holding Register for Reading and Writing INTxTMRH bits

REGISTER 17-20: INTxHLDL: INTERVAL TIMERx HOLD LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **INTHLD<15:0>:** Holding Register for Reading and Writing INTxTMRL bits

REGISTER 23-1: ADxCON1: ADCx CONTROL REGISTER 1 (CONTINUED)

bit 7-5 **SSRC<2:0>:** Sample Clock Source Select bits

If SSRCG = 1:

111 = Reserved
110 = PTGO15 primary trigger compare ends sampling and starts conversion(1)
101 = PTGO14 primary trigger compare ends sampling and starts conversion(1)
100 = PTGO13 primary trigger compare ends sampling and starts conversion(1)
011 = PTGO12 primary trigger compare ends sampling and starts conversion(1)
010 = PWM Generator 3 primary trigger compare ends sampling and starts conversion
001 = PWM Generator 2 primary trigger compare ends sampling and starts conversion
000 = PWM Generator 1 primary trigger compare ends sampling and starts conversion

If SSRCG = 0:

111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = CTMU ends sampling and starts conversion
101 = PWM secondary Special Event Trigger ends sampling and starts conversion
100 = Timer5 compare ends sampling and starts conversion
011 = PWM primary Special Event Trigger ends sampling and starts conversion
010 = Timer3 compare ends sampling and starts conversion
001 = Active transition on the INT0 pin ends sampling and starts conversion
000 = Clearing the Sample bit (SAMP) ends sampling and starts conversion (Manual mode)

bit 4 **SSRCG:** Sample Trigger Source Group bit

See SSRC<2:0> for details.

bit 3 **SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = 01 or 1x)

In 12-Bit Mode (AD12B = 1), SIMSAM is Unimplemented and is Read as '0':

1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x), or samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)
0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADCx Sample Auto-Start bit

1 = Sampling begins immediately after last conversion; SAMP bit is auto-set
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADCx Sample Enable bit

1 = ADCx Sample-and-Hold amplifiers are sampling
0 = ADCx Sample-and-Hold amplifiers are holding

If ASAM = 0, software can write '1' to begin sampling. Automatically set by hardware if ASAM = 1. If SSRC<2:0> = 000, software can write '0' to end sampling and start conversion. If SSRC<2:0> ≠ 000, automatically cleared by hardware to end sampling and start conversion.

bit 0 **DONE:** ADCx Conversion Status bit(2)

1 = ADCx conversion cycle is completed.
0 = ADCx conversion has not started or is in progress

Automatically set by hardware when A/D conversion is complete. Software can write '0' to clear DONE status (software not allowed to write '1'). Clearing this bit does NOT affect any operation in progress. Automatically cleared by hardware at the start of a new conversion.

Note 1: See **Section 25.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.
2: Do not clear the DONE bit in software if ADCx Sample Auto-Start bit is enabled (ASAM = 1).

REGISTER 27-4: RTCVAL (WHEN RTCPTR<1:0> = 11): YEAR VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN1	YRTEN0	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year's Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to the YEAR register is only allowed when RTCWREN = 1.

REGISTER 27-5: RTCVAL (WHEN RTCPTR<1:0> = 10): MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R-x	R-x	R-x	R-x	R-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of 0 or 1.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day's Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

30.2 User ID Words

dsPIC33EPXXXGM3XX/6XX/7XX devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information, such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 30-3.

TABLE 30-3: USER ID WORDS REGISTER MAP

File Name	Address	Bits<23:16>	Bits<15:0>
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

Legend: — = unimplemented, read as '1'.

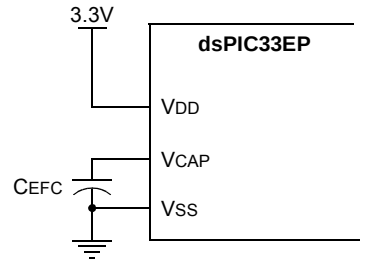
30.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGM3XX/6XX/7XX devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGM3XX/6XX/7XX family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 30-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 33-5, located in **Section 33.0 "Electrical Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 30-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 33-5 located in **Section 33.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 1.8V when VDD ≥ VDDMIN.

30.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the Power-up Timer (PWRT) Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 33-21 of **Section 33.0 "Electrical Characteristics"** for specific TFSCM values.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle mode and resets the device should VDD fall below the BOR threshold voltage.

32.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

32.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

33.1 DC Characteristics

TABLE 33-1: OPERATING MIPS vs. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Maximum MIPS
			dsPIC33EPXXXGM3XX/6XX/7XX
I-Temp	3.0V to 3.6V(1)	-40°C to +85°C	70
E-Temp	3.0V to 3.6V(1)	-40°C to +125°C	60

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, op amp/comparator and comparator voltage reference will have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

TABLE 33-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices:					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices:					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 33-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 121-Pin BGA	θJA	40	—	°C/W	1
Package Thermal Resistance, 100-Pin TQFP 12x12 mm	θJA	43	—	°C/W	1
Package Thermal Resistance, 100-Pin TQFP 14x14 mm	θJA		—	°C/W	1
Package Thermal Resistance, 64-Pin QFN	θJA	28.0	—	°C/W	1
Package Thermal Resistance, 64-Pin TQFP 10x10 mm	θJA	48.3	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN	θJA	29.0	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10 mm	θJA	49.8	—	°C/W	1
Package Thermal Resistance, 44-Pin VTLA 6x6 mm	θJA	25.2	—	°C/W	1
Package Thermal Resistance, 36-Pin VTLA 5x5 mm	θJA	28.5	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN-S	θJA	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θJA	71.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θJA	69.7	—	°C/W	1
Package Thermal Resistance, 28-Pin SPDIP	θJA	60.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 33-9: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.(2)**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (IDOZE)(1)							
DC73a	20	53	1:2	mA	-40°C	3.3V	70 MIPS
DC73g	8	30	1:128	mA			
DC70a	19	53	1:2	mA	+25°C	3.3V	60 MIPS
DC70g	8	30	1:128	mA			
DC71a	20	53	1:2	mA	+85°C	3.3V	60 MIPS
DC71g	10	30	1:128	mA			
DC72a	25	42	1:2	mA	+125°C	3.3V	50 MIPS
DC72g	12	30	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as outputs and driving low
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)
- CPU executing

```
while(1)
{
NOP();
}
```

- JTAG is disabled

2: Data in the “Typical” column is at 3.3V, +25°C unless otherwise specified.

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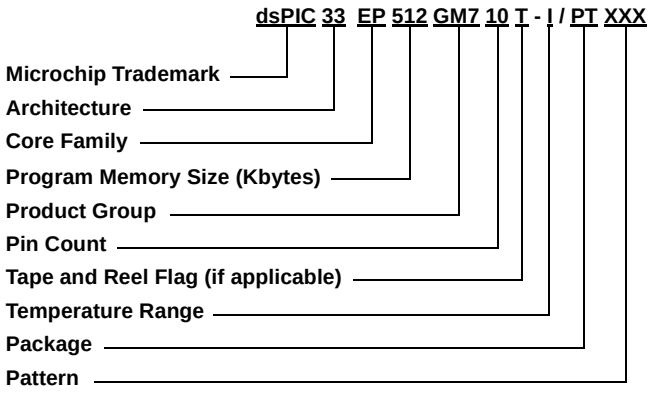
PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Architecture:	33	=	16-Bit Digital Signal Controller
Family:	EP	=	Enhanced Performance
Product Group:	GM7	=	General Purpose plus Motor Control Family
Pin Count:	04	=	44-pin
	06	=	64-pin
	10	=	100/124-pin
Temperature Range:	I	=	-40°C to +85°C (Industrial)
	E	=	-40°C to +125°C (Extended)
Package:	BG	=	Plastic Thin Profile Ball Grid Array - (121-pin) 10x10 mm body (TFBGA)
	ML	=	Plastic Quad, No Lead Package - (44-pin) 8x8 mm body (QFN)
	MR	=	Plastic Quad, No Lead Package - (64-pin) 9x9 mm body (QFN)
	PT	=	Plastic Thin Quad Flatpack - (44-pin) 10x10 mm body (TQFP)
	PT	=	Plastic Thin Quad Flatpack - (64-pin) 10x10 mm body (TQFP)
	PT	=	Thin Quad Flatpack - (100-pin) 12x12x1 mm body (TQFP)
	PF	=	Thin Quad Flatpack - (100-pin) 14x14x1 mm body (TQFP)

Example:

dsPIC33EP512GM710-I/PT:
dsPIC33, Enhanced Performance, 512-Kbyte program memory, 100-pin, Industrial temperature, TQFP package.

NOTES: